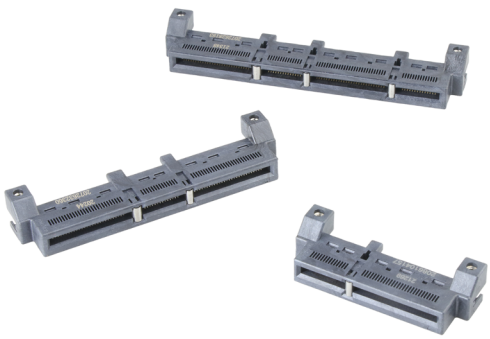
DATASHEET

# Sliver Edge-Card Receptacle and Cable Assemblies ›

**The versatile Sliver Edge-Card Receptacle, recognized by the Small Form Factor Committee (SFF), Open Compute Project (OCP) and CXL Consortium standards, offers various configurations for effective use in a wide variety of high-speed board-to-board, copper flex and cable applications**

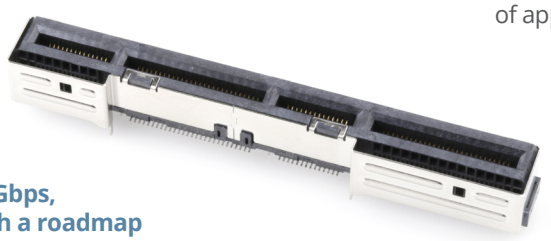


*Sliver Edge-Card Straddle-Mount Connector*

## FEATURES AND ADVANTAGES

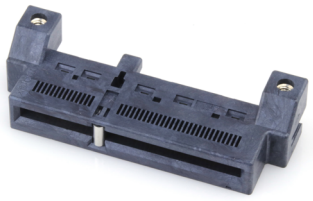
**Small 0.60mm pitch**
Offers a 30% space savings compared to a conventional 0.80mm-pitch solution

**A versatile connector for use across multiple platforms**
Adaptable for memory/storage, accessory cards and orthogonal direct configurations. Enables large-volume purchases for a variety of applications



**32 Gbps, with a roadmap to 56 Gbps**
Serves as a tiered, scalable solution

**Custom cable assemblies available**
Simplifies procurement by enabling the cable assembly to be purchased from the same vendor as the connector



**Recognized by several industry standards-the SFF, COBO, EDSFF and the Open Compute Project (OCP)**
Delivers known performance levels. Recognized as a proven industry-standard solution

## MARKETS AND APPLICATIONS

**Telecommunications/Networking**
Servers
Chassis
Interposer cards

**Smart Phones and Mobile Devices**
Mobile devices
AR/VR devices

**Connected Home**
IoT devices

*AR/VR Headset*

*Data Centers*

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## SPECIFICATIONS

### REFERENCE INFORMATION

Packaging: Tray
UL File No.: In Process
CSA File No.: In Process
Mates With: Sliver Edge Cards
Designed In: Millimeters
RoHS: Yes
Halogen Free: Yes
Glow Wire Compliant: No

### ELECTRICAL

Voltage (max.): 29V AC (RMS)/DC
Current (max.): 1.1A per Pin
Contact Resistance: 15 milliohms, Delta
Dielectric Withstanding Voltage: 300V AC
Insulation Resistance (max.): 1000 Megohms

### MECHANICAL

Contact Insertion Force (max.): 1.1N per Pin Pair
Unmating Force (min.): 0.08N per Pin Pair
Durability (min.): 200 Cycles

### PHYSICAL

Housing: LCP Plastic
Contact: Copper Alloy
Plating: Gold over Nickel over Copper Alloy
Contact Area — 0.76µm (30µ") Gold
Solder Tail Area — 2.54µm (100µ") Tin
Underplating — 1.27µm (50µ") Nickel Underplate
PCB Thickness: 1.57mm (0.062")
Operating Temperature: -45 to +85°C

**www.molex.com/link/Sliver.html**


Order No. 987652-0631 Rev. 5 USA/0k/GF/2023.01